

Company :

Company Name :

Nature Of Business :

Designation :

Tentative Job Location :

Taiwan Semiconductor Manufacturing Company

Taiwan Semiconductor Manufacturing Company

Semiconductor

Software and Data Engineer

Hsinchu City, Taiwan

Responsibilities

1. Development and integration of Cloud Computing, Kubernetes or BigData Analytics Systems

2. Build/Development Scalable Platform for managing container applications

3. Development utilities and applications for IT operation automation.

Requirements

1. Master degree of Computer Science, Information Management or Electrical Engineering.

2. Familiar with development of C/C++ or JAVA Programming, or

3. Familiar with Microservices Architecture Pattern, DevOps or

4. Familiar with Web Applications for PC and Mobiles, or

5. Familiar with Hadoop, Spark and Parallel Computing.

6. The ones with multiple above skill sets and experience will be a plus.

7. Experience with large-scale system integration, cloud computing, social networking for factory automation will be a plus

8. Self-motivated, integrity, aggressive and result-oriented personality.

Description :

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2. Familiar with development of C/C++ or JAVA Programming, or

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Eligibility :

Program	AE	BSBE	CE	CHE	CSE	EE	ES	ME	MSE	PHY	CHM	MTH	ECO	DES	IME	CGS	HSS	EEM	MSP	NET	PSE	Stats
BT	No	No	No	No	No	No	--	No	No	--	--	--	--	--	--	--	--	--	--	--	--	--
BS	--	--	--	--	--	--	No	--	--	No	No	No	No	--	--	--	--	--	--	--	--	--
MT	No	No	No	No	Yes	Yes	No	No	Yes	--	--	--	--	--	Yes	--	--	No	Yes	No	Yes	--
DoubleMajor	No	No	No	No	No	No	--	No	No	No	No	No	No	--	--	--	--	--	--	--	--	--
dual	No	No	No	No	Yes	Yes	No	No	Yes	No	No	Yes	No	--	--	--	--	--	--	--	--	--
dualB	No	No	No	No	Yes	Yes	--	No	Yes	No	No	Yes	No	--	Yes	--	--	No	--	No	Yes	--
dualC	No	No	No	No	Yes	Yes	No	No	Yes	No	No	Yes	No	No	Yes	--	--	--	--	--	--	--
Mdes	--	--	--	--	--	--	--	--	--	--	--	--	--	No	--	--	--	--	--	--	--	--
MBA	--	--	--	--	--	--	--	--	--	--	--	--	--	--	No	--	--	--	--	--	--	--
Phd	No	No	No	No	No	No	No	No	No	No	No	No	No	No	No	No	No	No	No	No	No	No
MSc	--	--	--	--	--	--	--	--	--	No	No	Yes	--	--	--	--	--	--	--	--	--	Yes
MSR	No	No	No	No	Yes	Yes	--	No	Yes	--	--	--	--	--	--	No	--	--	--	--	Yes	--

Cost to Company :

Item (Annual)	Master Degree
GROSS	\$ 48,533
CTC	\$ 51,566

Currency: USD

Package Details :

1. Including 12 months base pay, 2 months Year-end bonus, 18 months Profit Sharing, 2 months relocation bonus, months of sign on bonus (depends on whether the offer has bond).

2. Base Salary, Year-end bonus are fixed and recurring ; Profit Sharing is minimum amount for an average performance (i.e. top 50%) and recurring. ; Relocation and sign on bonus are one shot paid after onboard.

3. Please note that the "Bond duration" is just for reference. The actual duration will depend on the offer that you get, it would be determined by your hiring manager.

Bond :

CPI CutOff :

Bond Details :

Medical Requirments :

Resume Shortlist :

Resume Shortlist Criteria:

Aptitude Test:

Group Discussion:

Technical Test:

Technical Interview:

Technical Interview Duration:

Number of Techincal Interview

True

0.0

May have bond but it depends on further hiring assessment. (will be determined by the hiring manager)

True

None

False

False

False

True

60 min

1

Rounds:

**HR
Interview:**

True

**HR
Interview
Duration:**

60 min

**Additional
Information:**